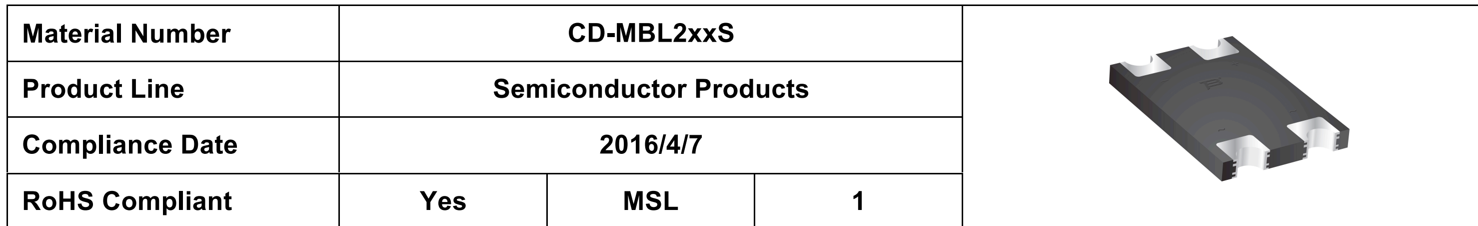
MATERIAL DECLARATION SHEET



Material Number	CD-MBL2xxS		
Product Line	Semiconductor Products		
Compliance Date	2016/4/7		
RoHS Compliant	Yes	MSL	1

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	FRP	Metal	74.130	Continuous filament glass fibers	65997-17-3	43.00	28.978	67.391
				Copper foil	7440-50-8	14.00	9.435	
				Non-Hazardous cured resin	Proprietary	43.00	28.978	
2	Epoxy	Plastic	19.690	Silicon Dioxide	7631-86-9	55.00	9.845	17.900
				Epoxy resin	9003-36-5	45.00	8.055	
3	Solder Cream	Metal	1.523	Lead[2]	7439-92-1	88.00	1.218	1.384
				Tin	7440-31-5	10.00	0.138	
				Silver	7440-22-4	2.00	0.028	
4	Dice	Metal	12.457	Silicon	7440-21-3	35.77	4.051	11.325
				Nickel	7440-02-0	0.70	0.080	
				Lead-containing glass[3]	7439-92-1	63.51	7.192	
				Gold	7440-57-5	0.02	0.002	
5	Terminal Plating	Metal	2.200	Tin	7440-31-5	100	2.000	2.000
		Total weight	110.000					

This Document was updated on: 2016/4/7

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Important remarks:

1. **It is the responsibility of the user to verify they are accessing the latest version.**
2. **Excepted for RoHS 7(a) – (Lead in high temp solder)**
3. **Excepted for RoHS 7(c) I – (Lead in glass)**

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